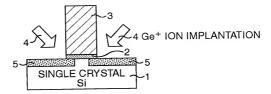
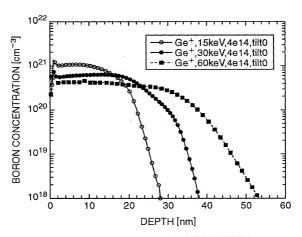
FIG. 1

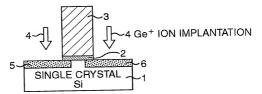


PARTS UNDER GATE ELECTRODE ALSO AMORPHOUSIZED BY OBLIQUE AMORPHOUSIZING IMPLANTATION (IMPURITIES IN THESE PARTS ACTIVATED)

FIG. 2



SECONDARY ION MASS SPECTROMETRY



SOURCE/DRAINS HAVING PARTS UNDER GATE ELECTRODE ALSO AMORPHOUSIZED FORMED BY CONTROLLING ION IMPLANTATION CONDITION AND LASER IRRADIATION CONDITION (IMPURITIES IN THESE PARTS ACTIVATED)

FIG. 4

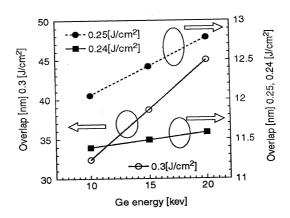
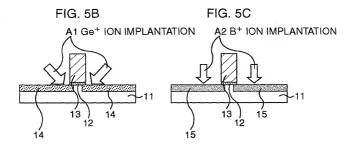


FIG. 5A

13

12

SINGLE CRYSTAL Si 11



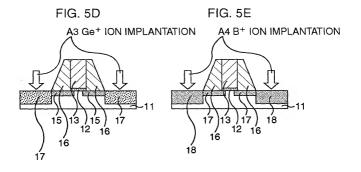


FIG. 6A

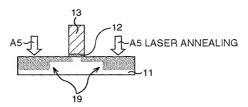


FIG. 6B

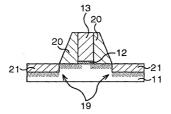
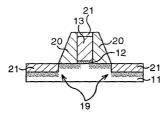
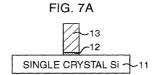


FIG. 6C





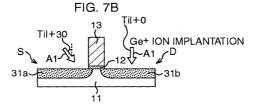


FIG. 7C

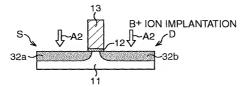


FIG. 7D

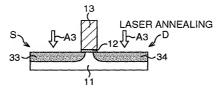


FIG. 8A SINGLE CRYSTAL Si

FIG. 8B

FIG. 8C

Ge+ ION IMPLANTATION 11

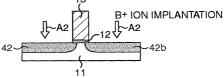


FIG. 8D LASER ANNEALING 11

